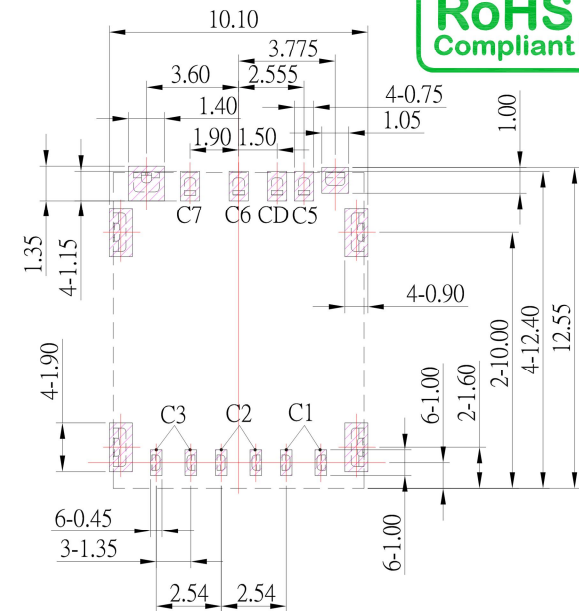
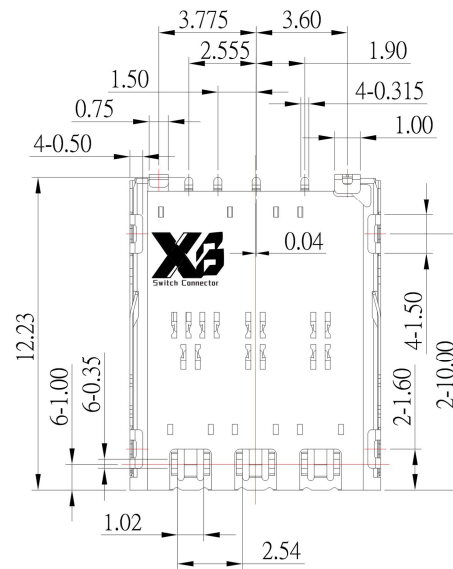
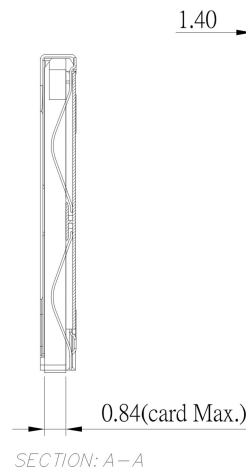
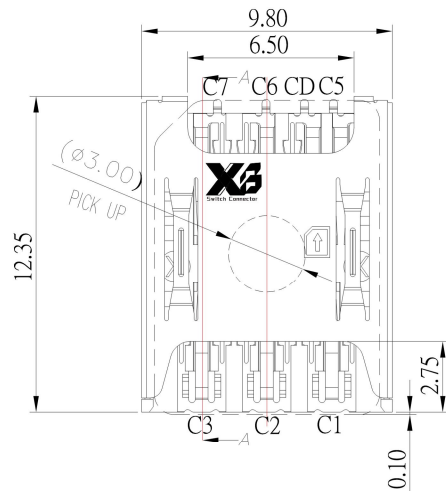
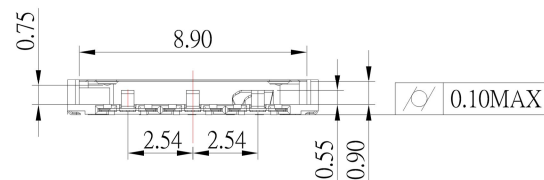




▨ SMT SOLDER AREA.
□ CONNECTOR AREA

P.C.B LAYOUT MOUNTING PATTERN

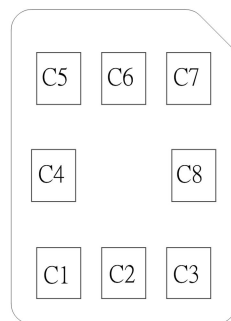


SW Circuit Description for Connector:

CARD INSERTION STATE	DETECT SWITCH CIRCUIT STATE	SCHEMATIC
UNMATED	OPENED	DETECT PIN [C2] - [C5]
MATED	CLOSED	DETECT PIN [C2] - [C5]

Nano SIM Circuit Description:

PIN No.	FUNCTION
C1	VCC
C2	RST
C3	CLK
C4	RESERVED
C5	GND
C6	VPP
C7	I/O
C8	RESERVED



MATERIALS:

1. HOUSING : LCP
2. CONTACT : PHOSPHOR BRONZE
3. SHELL : SUS

Finish:

1. Finish: CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
2. SHELL: NICKEL UNDER PLATED SURFACE LAYER

SPECIFICATION:

1. CURRENT RATING : 0.5A MAX.
2. VOLTAGE RATING : 5.0V AC / DC
3. INSULATION RESISTANCE : 1000MΩ MIN.
4. CONTACT RESISTANCE : 100mΩ MAX.
5. OPERATING TEMPERATURE RANGE : -40°C TO +85°C.
6. STORAGE TEMPERATURE RANGE : -40°C TO +85°C.



东莞市溪榜电子有限公司
DONG GUAN XI BANG ELECTRONICS CO., LTD.

TOLERANCE UNLESS OTHERWISE STATED:
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 03/23/23
DATE: 03/23/23
DATE: 03/23/23

MAT'L
FINISH
SCALE
SHEET NO.

1 : 1
1 of 1

TITLE
MODLE
DWG NO.
PART NO.

CONNECTOR
Nano SIM CARD PUSH PUSH 1.40H
NSIM-111308-S267
NSIM-111308-S267

SIZE
A4
VER
R

ITEM NO. DESCRIPTION DRAWN DATE